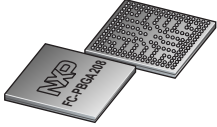


SOT2175-1

FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

26 March 2026

Package information



1 Package summary

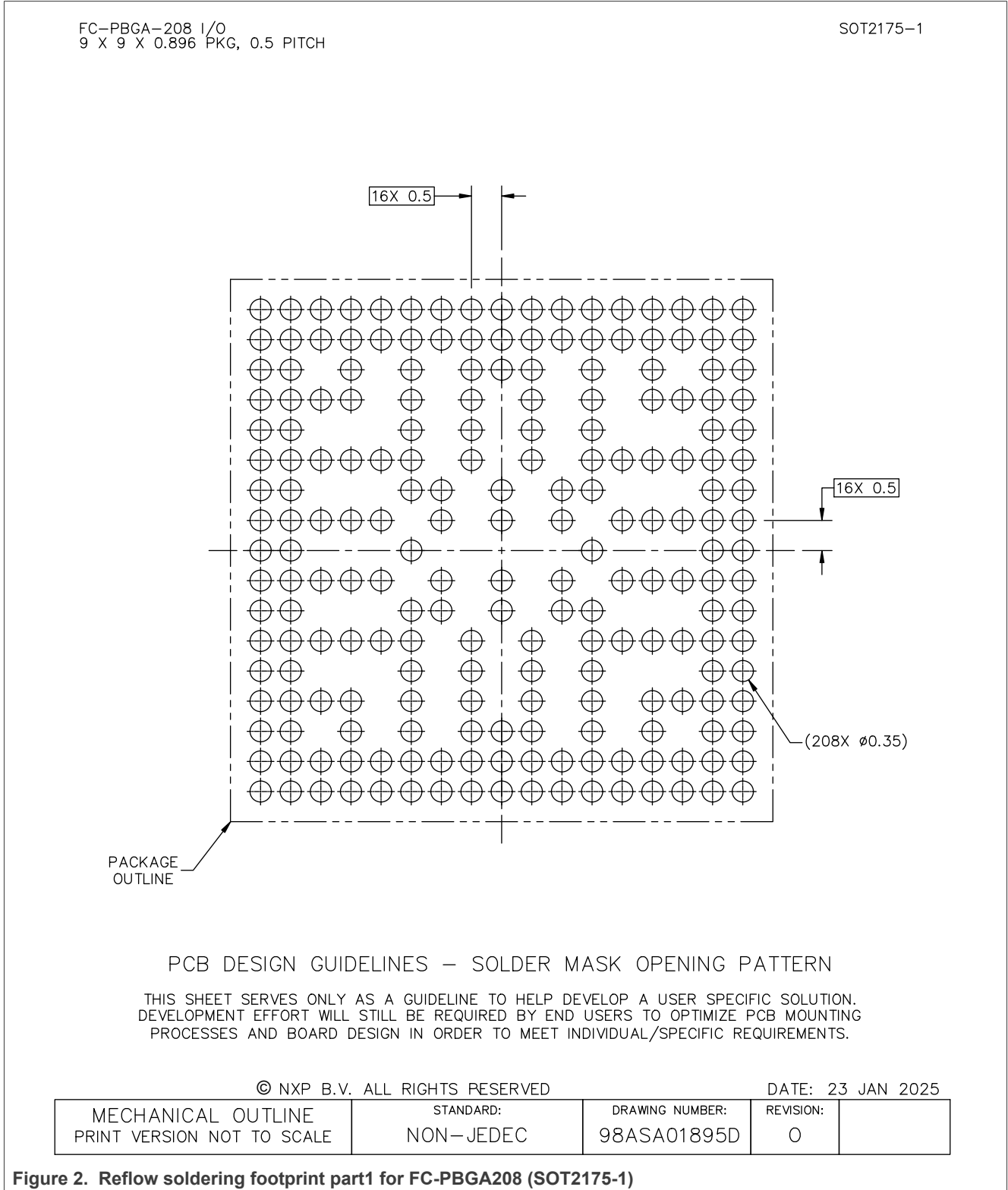
Terminal position code	B (bottom)
Package type descriptive code	FC-PBGA208
Package style descriptive code	FC-PBGA (flip chip - plastic ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-01-2025
Manufacturer package code	98ASA01895D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.85	9	9.15	mm
package width	8.85	9	9.15	mm
seated height	0.792	0.896	1	mm
nominal pitch	-	0.3	-	mm
actual quantity of termination	-	208	-	



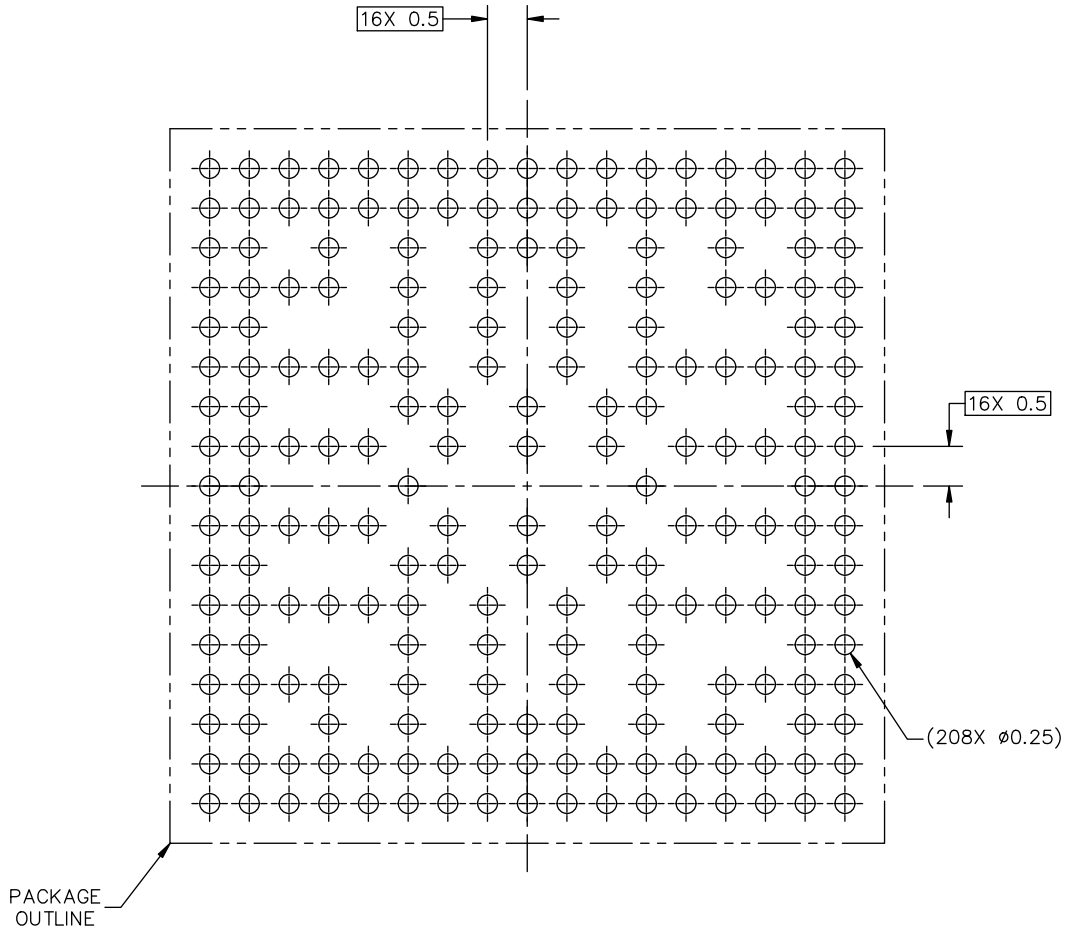
3 Soldering



FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

FC-PBGA-208 I/O
9 X 9 X 0.896 PKG, 0.5 PITCH

SOT2175-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 23 JAN 2025

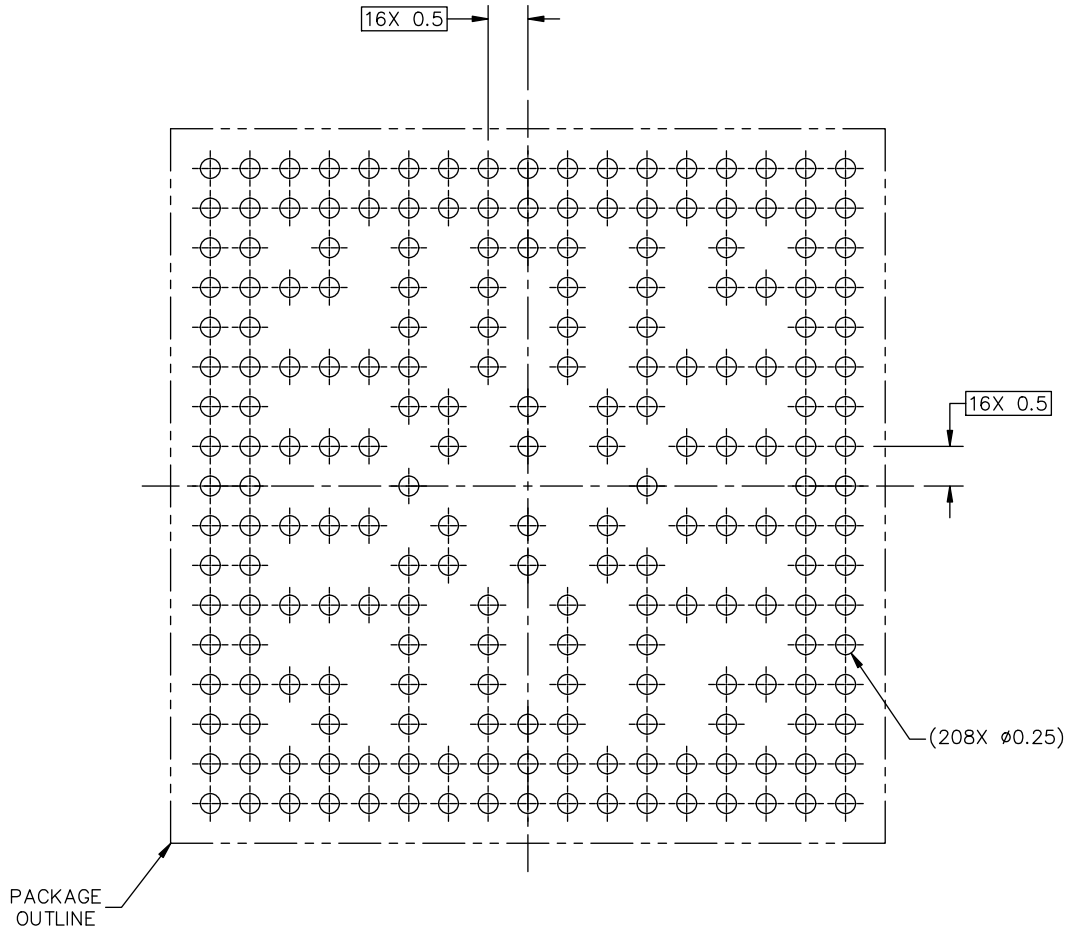
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01895D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for FC-PBGA208 (SOT2175-1)

FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

FC-PBGA-208 I/O
9 X 9 X 0.896 PKG, 0.5 PITCH

SOT2175-1



RECOMMENDED STENCIL THICKNESS 0.08

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01895D	REVISION: 0	
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Figure 4. Reflow soldering footprint part3 for FC-PBGA208 (SOT2175-1)

FC-PBGA208, flip chip - plastic ball grid array, 208 terminals, 0.3 mm pitch, 9 mm x 9 mm x 0.896 mm body

FC-PBGA-208 I/O
9 X 9 X 0.896 PKG, 0.5 PITCH

SOT2175-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 23 JAN 2025

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01895D	REVISION: 0	
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Figure 5. Package outline note FC-PBGA208 (SOT2175-1)

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